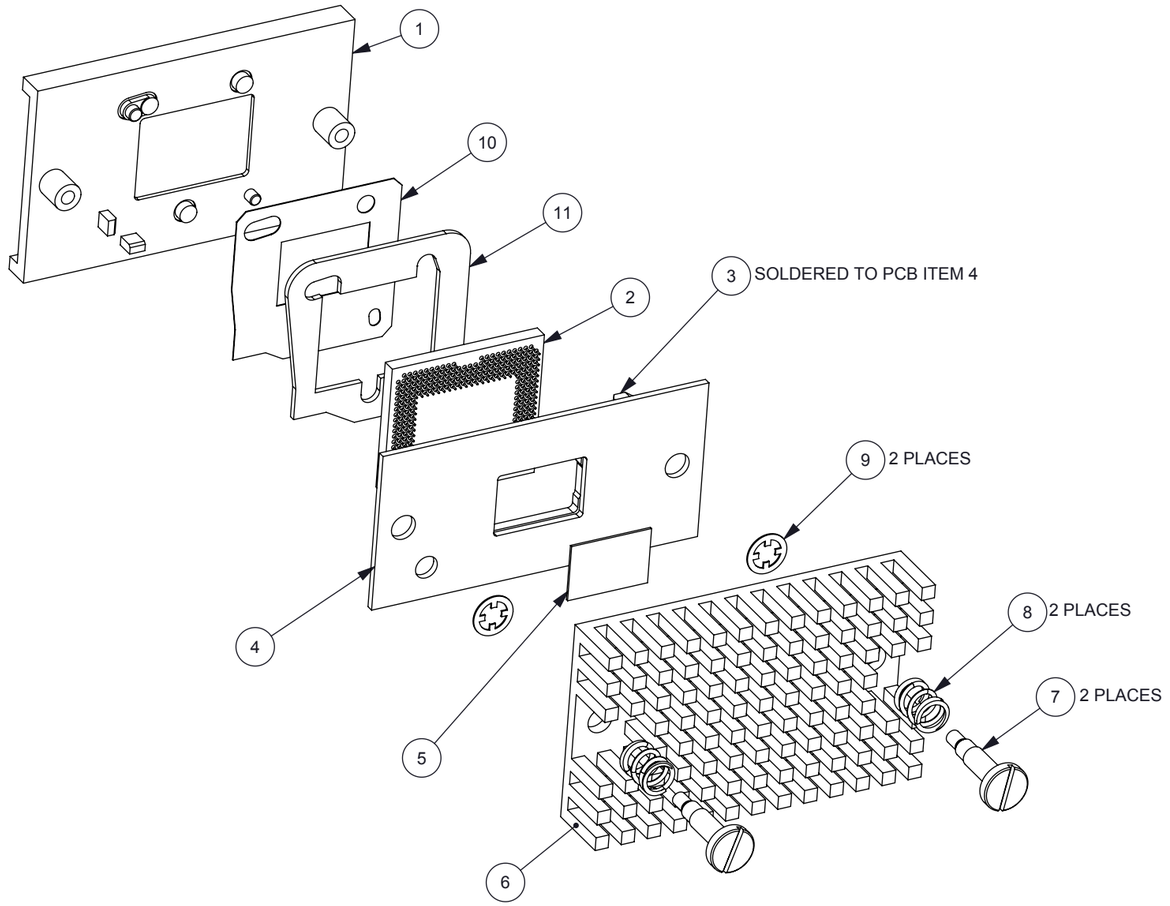
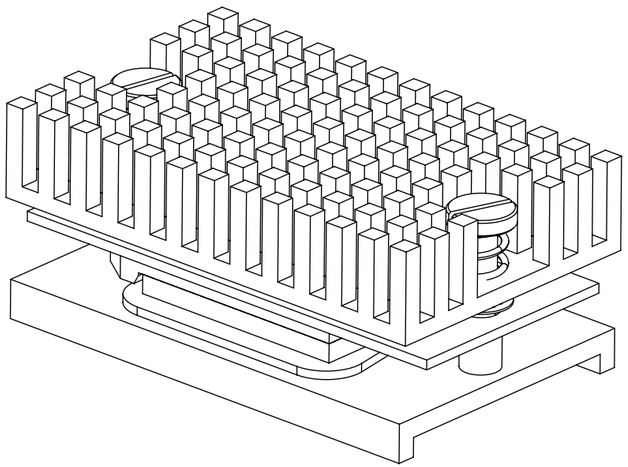
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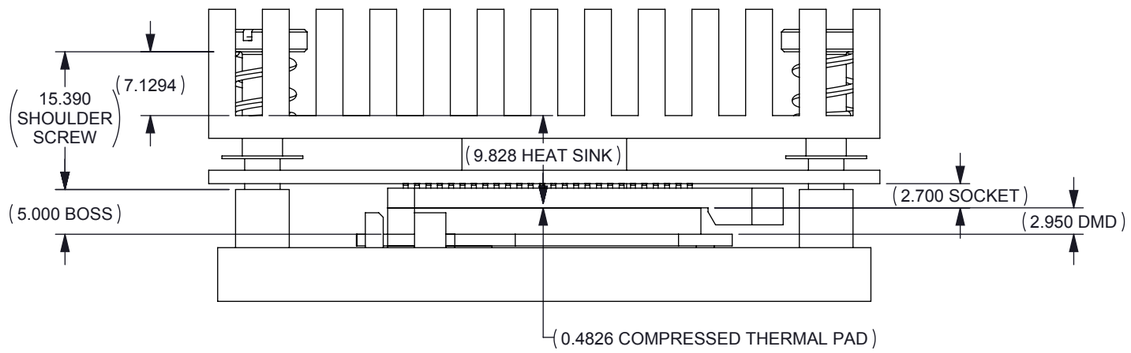
REVISIONS			
REV	DESCRIPTION	DATE	BY
A	INITIAL RELEASE	9/20/2014	JTM

NOTES: UNLESS OTHERWISE SPECIFIED:

1. SOME TYPE OF SUPPORT FOR THE DMD PC BOARD IS DESIRED TO ASSURE THE PC BOARD IS SECURED IN POSITION TO MAINTAIN THE DMD ELECTRICAL CONNECTION AFTER MECHANICAL SHOCK AND VIBRATION. SEE TI DRAWING 2507519 FOR CONCEPT IDEAS. CARE SHOULD BE TAKEN TO ENSURE THE METHOD DOES NOT APPLY LOADS TO THE DMD THAT EXCEED SPECIFICATION LIMITS.
2. CARE SHOULD BE TAKEN WHEN INSTALLING THE DMD TO NOT DAMAGE THE DMD WINDOW DUE TO THE CLOSE PROXIMITY OF THE ALIGNMENT AND GUIDE FEATURES ON THE INTERFACE.







REF	12	2507519	DMD PC BOARD SUPPORT CONCEPTS	1
1	11	2511728	GASKET, SYSTEM, SERIES 600	
1	10	2511727	APERTURE, SERIES 600 SYSTEM	
2	9	5105-15 (TRUARC)	RETAINER, PUSH NET	
2	8	LC042E01S (LEE SPRING)	SPRING, COIL	
2	7	2511633	SCREW, SHOULDER	
1	6	2511635	HEAT SINK, FEATURE CONCEPT	
1	5	2511634	THERMAL PAD, SERIES 600	
1	4	2511637	ASSEMBLY, PCB, SERIES 600	
1	3	2511569	SOCKET, SERIES 600 ZIF	
1	2		SERIES 600 DMD	
1	1	2511631	INTERFACE, SERIES 600 SYSTEM, EDGE GUIDE	
QTY	ITEM	PART NUMBER	DESCRIPTION	Notes

Part List

THIRD ANGLE PROJECTION

NONE	0314RD
NEXT ASSY	USED ON
APPLICATION	

UNLESS OTHERWISE SPECIFIED
- DIMENSIONS ARE IN MILLIMETERS
- TOLERANCES: ANGLES ±1°
  2 PLACE DECIMALS ±0.25
  1 PLACE DECIMALS ±0.50
- DIMENSIONAL LIMITS APPLY BEFORE PROCESSES
- INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994
- REMOVE ALL BURRS AND SHARP EDGES
- PARENTHETICAL INFO FOR REF ONLY

TEXAS INSTRUMENTS

SYSTEM INTERFACE CONCEPT ASSEMBLY, EDGE GUIDE, SERIES 600

SIZE	DWG NO	REV
B	2511654	A
SCALE 2:1	SHEET 1 OF 2	

SW-2012a

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SSZZ031 January 01, 2013